L Number	Hits	Search Text	DB	Time stamp
1	2	6490368.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/05 11:33
6	10	382/147	US-PGPUB	2003/09/05 11:42
-	2	4926452.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/05 11:33
-	2	5081656.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/30 23:20
-	2	5097492.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/30 23:20
-	2	5199054.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/30 23:21
-	2	5259012.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/30 23:22
-	2	5291535.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/30 23:22
-	2	5561696.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/30 23:23
-	2	5583904.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/30 23:24
-	2	5621811.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/30 23:41
-	2	5687209.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/30 23:25
-	118	378/22.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/30 23:30
-	216	382/147.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/30 23:30

-	324	378/21.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/30 23:31
-	1287	(identify$3 or inspect$3 or evaluat$3) with solder$3 with (joint$1 or connection$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/31 00:17
-	21	((identify$3 or inspect$3 or evaluat$3) with solder$3 with (joint$1 or connection$1)) and ((distance or space or gap) with (mount$3 with surface$1 with board))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/05 11:42
-	65	((identify$3 or inspect$3 or evaluat$3) with solder$3 with (joint$1 or connection$1)) and ((distance or space or gap) with (surface$1 with board))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/31 00:07
-	5	((identify$3 or inspect$3 or evaluat$3) with solder$3 with (joint$1 or connection$1)) and (neighbor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/31 00:08
-	683	((distance or space or gap) with (mount$3 with surface$1 with board) same (printed with circuit))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/31 00:17
-	612	((distance or space) with (mount$3 with surface$1 with board) same (printed with circuit))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/31 00:17
-	10	((((distance or space or gap) with (mount$3 with surface$1 with board) same (printed with circuit))) and ((defect$1 or quality) with solder$3 with (joint$1 or connection$1))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/31 00:27
-	0	((identify$3 or inspect$3 or evaluat$3) with solder$3 with (joint$1 or connection$1)) and (box adj plot)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/31 00:28
-	73	box adj plot	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/31 00:28
-	64	(box adj plot) and (analy$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/31 00:28
-	1	((box adj plot) and (analy$4)) and (solder)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/31 00:28
-	185363	(chang$3 or adjust$3 or adapt$3 or calculat$3 or alter$3 or modif$4 or set$4) with (threshold or criteria)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/03 15:18

-	33687	((chang$3 or adjust$3 or adapt$3 or calculat$3 or alter$3 or modif$4 or set$4) with (threshold or criteria)) and ((defect$3 or fault$1 or error$1 or quality) with (inspect$3 or check$3 or detect$3 or test$3 or examin$5))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/03 15:25
-	3	(((chang$3 or adjust$3 or adapt$3 or calculat$3 or alter$3 or modif$4 or set$4) with (threshold or criteria)) and ((defect$3 or fault$1 or error$1 or quality) with (inspect$3 or check$3 or detect$3 or test$3 or examin$5))) and (((printed adj circuit adj board) with solder with joint$1) same ((location or position) with solder with (joint$1 or connection$1)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/03 15:26
-	1	((((chang$3 or adjust$3 or adapt$3 or calculat$3 or alter$3 or modif$4 or set$4) with (threshold or criteria)) and ((defect$3 or fault$1 or error$1 or quality) with (inspect$3 or check$3 or detect$3 or test$3 or examin$5))) and (((printed adj circuit adj board) with solder with joint$1) same ((location or position) with solder with (joint$1 or connection$1)))) and ((distance or space) with mount$3 with surface with board with device)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/03 15:56
-	438825	((defect$3 or fault$1 or error$1 or quality) with (inspect$3 or check$3 or detect$3 or test$3 or examin$5))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/03 15:25
-	49	(((printed adj circuit adj board) with solder with joint$1) same ((location or position) with solder with (joint$1 or connection$1)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/03 15:53
-	380	((distance or space) with mount$3 with surface with board with device)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/03 15:27
-	1	((((printed adj circuit adj board) with solder with joint$1) same ((location or position) with solder with (joint$1 or connection$1)))) and (((distance or space) with mount$3 with surface with board with device))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/03 15:27
-	92	(((printed adj circuit adj board) with solder with joint$1) and ((location or position) with solder with (joint$1 or connection$1)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/03 16:03
-	6	(((chang$3 or adjust$3 or adapt$3 or calculat$3 or alter$3 or modif$4 or set$4) with (threshold or criteria)) and ((defect$3 or fault$1 or error$1 or quality) with (inspect$3 or check$3 or detect$3 or test$3 or examin$5))) and ((((printed adj circuit adj board) with solder with joint$1) and ((location or position) with solder with (joint$1 or connection$1))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/03 15:56

-		1	((((chang$3 or adjust$3 or adapt$3 or calculat$3 or alter$3 or modif$4 or set$4) with (threshold or criteria)) and ((defect$3 or fault$1 or error$1 or quality) with (inspect$3 or check$3 or detect$3 or test$3 or examin$5))) and ((((printed adj circuit adj board) with solder with joint$1) and ((location or position) with solder with (joint$1 or connection$1))))) and ((distance or space) with mount$3 with surface with board with device)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/03 15:56
-	1514		((location or position) with solder with (joint$1 or connection$1))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/03 16:03
-	239		((distance or space) with mount$3 with surface with (circuit with board) with device$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/03 16:04
-		1	((((chang$3 or adjust$3 or adapt$3 or calculat$3 or alter$3 or modif$4 or set$4) with (threshold or criteria)) and ((defect$3 or fault$1 or error$1 or quality) with (inspect$3 or check$3 or detect$3 or test$3 or examin$5))) and (((location or position) with solder with (joint$1 or connection$1)))) and (((distance or space) with mount$3 with surface with (circuit with board) with device$1))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/03 16:05
-		5	((((location or position) with solder with (joint$1 or connection$1))) and (((distance or space) with mount$3 with surface with (circuit with board) with device$1))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/03 16:06
-		21	(((chang$3 or adjust$3 or adapt$3 or calculat$3 or alter$3 or modif$4 or set$4) with (threshold or criteria)) and ((defect$3 or fault$1 or error$1 or quality) with (inspect$3 or check$3 or detect$3 or test$3 or examin$5))) and (((location or position) with solder with (joint$1 or connection$1)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/04 11:53
-		1	((distance adj between) with (mounting adj surface) with device with (circuit adj board) with solder with (joint$1 or connection$1)) and (location or position)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/04 15:36
-		1	((distance or space) with (mounting adj surface) with device with (circuit adj board) with solder with (joint$1 or connection$1)) and (location or position)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/04 15:38
-		3	((distance or space) with (moun$3 with surface) with device with (circuit adj board) with solder with (joint$1 or connection$1)) and (location or position)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/04 15:39
-		8	((distance or space or gap) with surface with device with (circuit adj board)) and (solder with (joint$1 or connection$1))and (location or position)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/04 16:17

-	3	(((distance or space or gap) with surface with device with (circuit adj board)) and (solder with (joint$1 or connection$1))and (location or position)) and (threshold or criteria or range or limit)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/04 15:53
-	1	((distance or space) with (mounting adj surface) with device with (circuit adj board) with solder with (joint$1 OR connection$1)) AND (location OR position)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/04 15:53
-	84	((distance or space or gap) with surface with device with (circuit adj board)) and (solder with (joint$1 or connection$1))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/05 07:30
-·	1	RE35,423.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/05 07:32
-	2	6,580,501.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/05 07:31
-	2	5,780,866.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/05 07:31
-	2	4,792,683.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/05 07:31
-	219	702/35.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/05 11:26
-	181	702/33.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/05 11:26